SPARC activities at Roma2

INFN-Roma2 (L.Catani)

Status of Emittance-Meter system

Meeting on SPARC Emittance-Meter - 11 March 2004

Participants: L.Catani, G. Di Pirro, V.Fusco, E.Chiadroni, A.Cianchi, M.Castellano, D.Filippetto, S.Tazzari, A.Clozzza, M. Ferrario

Status Report from A.Clozza:

Pepper-pot machined and delivered to LNF

It still needs to be cleaned

Order for bellows signed (~25 kEUR):

- 2 x long bellows
- I x short
- 3 months delivery times

Minimum distance from cathode to pepper will be ~83cm Design of the overall system in under way and should be completed in few weeks.

Discussion

	the possibility of tilting the pepper-pot holder is considered as not critical. The angular acceptance is large enough (25 mrad) to avoid any disturbance to the measurement if the pepper-pot will be properly aligned.	
requirement	Simulations including tilted pepper-pot	
	should be carried out (A.Cianchi) to confirm this	
	analysis providing more detailed information	
	Steerings are desirable to correct beam	
	misalignment in the long e-meter structure	
requirement	Vertical resolution of the pepper-pot position	
	must be better than 25 µm provided the accuracy	
	of the movement is <2µm	
	Speed of vertical movement is not an issue	
requirement	4-phase stepper motor 200 steps/turn	
requirement	Absolute Optical Encoder: accuracy must be	

For the fluorescent/YAG screen a three positions movement (out, in, calibration) will be sufficient. Precision of the movement is not an issue though the same mechanical components as for the pepper-pot could be used for compatibility. Some calibration system (either a calibration target or	
some calibration marks on the screen frame) will be needed and it must be discussed.	
YAG screen with back-observation is so far preferred to ceramic screen	
Performances and limitations of YAG screen have been discussed taking into account results available in the literature. Calibration of YAG radiator should be performed to evaluate the possible dependency of the beam size with the beam charge density. We should consider to buy a set of crystals to be measured at BTF.	
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Multislit Pepper Pot





Multislit Pepper-Pot machining accuracy

	slit#	size (mm)	exp. (mm)	err (mm)
100 <i>µ</i> m	1	0.0960	0.1000	0.0040
	spacer	9.9600	10.0000	0.0430
50µm	2	0.0470	0.0500	0.0030
	spacer	9.9700	10.0000	0.0290
	3	0.0470	0.0500	0.0030
	spacer	0.4640	0.5000	0.0360
	4	0.0470	0.0500	0.0030
	spacer	0.4700	0.5000	0.0300
	5	0.0430	0.0070	
array of	spacer	0.4590	0.5000	0.0410
$50\mu m$ slits	6	0.0350	0.0500	0.0150
	spacer	0.4580	0.5000	0.0420
	7	0.0500	0.0500	0.0000
	spacer	0.4640	0.5000	0.0360
	8	0.0460	0.0500	0.0040
	spacer	0.4580	0.5000	0.0420
	9	0.0420	0.0500	0.0080



Multislit Pepper-Pot (relative errors)

	slit#	size (mm)	exp. (mm)	err (mm)
100 <i>µ</i> m	1	0.0960	0.1000	0.0400
	spacer	9.9600	10.0000	0.0043
50µm	2	0.0470	0.0500	0.0600
	spacer	9.9700	10.0000	0.0029
	3	0.0470	0.0500	0.0600
	spacer	0.4640	0.5000	0.0720
	4	0.0470	0.0500	0.0600
	spacer	0.4700	0.5000	0.0600
	5	0.0430	0.0500	0.1400
array of	spacer	0.4590	0.5000	0.0820
$50\mu m$ slits	6	0.0350	0.0500	0.3000
	spacer	0.4580	0.5000	0.0840
	7	0.0500	0.0500	0.0000
E	spacer	0.4640	0.5000	0.0720
	8	0.0460	0.0500	0.0800
	spacer	0.4580	0.5000	0.0840
	9	0.0420	0.0500	0.1600



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Status of PCI-PCI Link development

Meeting on PCI-PCI link for the SPARC DAQ/Control System - 11 March 2004 Participants: L.Catani, G. Di Pirro, M.Castellano, A.Salamon, E.Gabrielli, M.Sabene, G.Salina, A.Stecchi

Status Report from A.Salamon:

Board developed for 64 bit/66Mhz PCI
Compatible (in principle) with PCI-X (64bit/133Mhz)
On-board memory: single-chip SRAM are available with either I Mbyte dual-port or 8 Mbytes single-port. Performances of the PCI-PCI link depends on the choice of the SRAM memory type
2 Mbits bi-directional fiber-optic link has been chosen

Discussion

Single-port SRAM is cheaper than dual-ported counterpart. One 8 Mbyte s-p SRAM cost approx. the same as on 1 Mbyte d-p SRAM (~200 EUR)d-p SRAM allows simultaneous read (from PCI) and write (from f.o. link) maximizing the overall data throughput. In this case some control on the memory access must be foreseen to avoid conflicts when R/Writing the same memory location. This functionality should be provided by the on-board FPGAs-p SRAM doesn't support simultaneous R/W; as consequence the above conflict cannot take place. The main disadvantage is the reduced PCI-PCI data throughput. It is in principle halved but this figure can be slightly improved reading data as longwords (they are written 16 bits)A second level of handshaking is needed to assure data consistency when R/Writing the same block of memory locations (e.g. when a local application is reading a data block being currently updated with data received from the f.o. channel)Any conflict due to simultaneous access to the same	Discussio	n	
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Any conflict due to simultaneous access to the same		consistency when R/Writing the same block of memory locations (e.g. when a local application is reading a data block being currently updated with data received from	
		Any conflict due to simultaneous access to the same	

	memory location/block must be solved giving priority to the writing process, i.e. (new) data coming from the f.o. channel	
decision	An on-board memory of I Mbyte has been considered as appropriated for most of the applications foreseen in the SPARC DAQ and control system. Larger memory size might be needed only for large data structure as 16-bit 640x480 image maps. Standard 8-bit 640x480 images will fit into a I Mbyte mirrored-memory This solution will provide the maximum achievable data throughput.	
decision	 Next step of the development will focus on: Designing a PCI-PCI I Mbyte mirrored-memory Evaluate the compatibility of the above design with extended on-board memory up to 4 Mbytes 2 Mbits f.o. link 	
	Cost of a set of PCI-PCI link should cost ~2.5 kEUR to be compared with ~5 kEUR of the commercial competitor.	
decision	So far only unidirectional data transfer has been taken into account. This feauture is sufficient for DAQ application of the PCI-PCI link The possibility to have bidirectional memory-mirroring must be discussed	
decision	A set of boards (at least two) will be ready to be tested with DAQ and Control System applications in 6 months	
	Next meeting will be scheduled when new results from the Roma2 group will be available	





e-LogBook

 e-LogBook for SPARC (based on TTF e-LogBook) has been developed and is operational on a temporary server (http:// elog.roma2.infn.it/MYelog/index.jsp)



WBS for the Emittance-meter

					2004	2005	2006
topics	sub-topic	milestones	w	ho	gfmamglasond	g f mamg las on d	g f mamglas on o
		31-12-2004					
		31-12-2004					
	progettazione	15-02-2004	LNF	RM2			
neccanica e vuoto	offerte	15-05-2004	LNF	RM2			
	ordini	30-06-2004	LNF	RM2			
	realizzazione	31-10-2004	LNF				
est fenditure		31-10-2004	LNF	RM2			
		31-10-2004					
novimenti longitudinali e	progettazione	30-06-2004	LNF	RM2			
liscendenti targhette motori stepper,	offerte	15-07-2004	LNF	RM2			
elettronica)	ordini	31-07-2004	LNF				
	realizzazione	31-10-2004	LNF	RM2			
		31-10-2004					
	ordini hardware per sviluppo e prog.	1-01-2004		RM2	*		
elecamera e sistema ottico	progettazione	30-06-2004		RM2			
	offerte	15-07-2004		RM2			
	ordini	31-07-2004	LNF				
	realizzazione	31-10-2004	LNF	RM2			
		31-11-2004					
	progettazione	30-06-2004	LNF	RM2			
acquisizione	offerte	15-07-2004	LNF	RM2			
	ordini	31-07-2004	LNF		*		
	realizzazione	31-11-2004	LNF	RM2			
software di analisi	realizzazione	30-10-2004		RM2			

OTR diagnostics

					2004	2005	2006
		31-12-2005			g f mamg lason d	g f mamglas on d	g f mamglas on
		31-12-2005					
	ordine telecamera per tests	31-10-2004		RM2	*		
elecamera alta sensibilità	test telecamera	30-06-2005	LNF	RM2			
	ordine telecamera scelta	15-07-2005	LNF				
	collaudo e installazione	31-12-2005	LNF	RM2			
		30-07-2005					
	ordini obb.macro per sviluppo	1-01-2004		RM2	*		
obbiettivo MACRO	studio e test	31-12-2004		RM2			
	offerte	15-01-2005		RM2			
	ordini	31-01-2005	LNF				
	realizzazione	30-07-2005	LNF	RM2			
		31-07-2005					
	progettazione	31-12-2004*	* dipende dalla	RM2		*	
emotizzazione obbiettivo MACRO	offerte	15-01-2005	disponibilit	RM2			
	ordini	31-01-2005	LNF				
	realizzazione	30-07-2005	LNF	RM2			
		31-07-2005					
	ordine sistema di sviluppo (componenti ottiche)	1-06-2004		RM2	*		
istemi ottici	progettazione	31-03-2005		RM2			
	offerte	15-04-2005		RM2			
	ordini	31-04-2005	LNF				
	realizzazione	31-07-2005	LNF	RM2			

Controls

						20	04				200	5				2006	5	
		31-03-2006			g	f ma mg	las	sond	g f	m a	mg l	a s	ond	g f	<mark>m</mark> a	mg l	a s	on
		31-05-2004																
Console system	ordini hardware per sviluppo	1-01-2004		RM2	*													
	test e progettazione	31-05-2004		RM2														
		31-10-2004																
e-Logbook	sviluppo e test	30-06-2004		RM2														
C 209200R	installazione e attivazione	31-10-2004		RM2														
		31-03-2006																
	test prototipo	31-10-2005	LNF	RM2														
DAQ	progettazione	31-12-2005	LNF	RM2														
	offerte	15-01-2006	LNF	RM2														
	ordini	1-02-2006	LNF	RM2														
	realizzazione	31-03-2006	LNF	RM2														

		Hesp. IOC.: Luciano Ca	tanı						
		RM2							
PREVENTIVO LOCALE DI SPESA PER L'ANNO 2004 In KEuro									
VOCI					IPORTI		A cura della Comm.ne		
DI SPESA		DESCRIZIONE DELLA SPESA		sian SJ	Totale Compet.		Scientifica Nazionale		
Vlaggi e missioni	Interno	meeting collaborazione, sviluppo e collaudo a LNF di componenti	3.0		3.0	0.0			
	Estero	conferenze (EPAC, PCaPAC) collaborazione con DESY/Zeuthen e incontri scientifici	5.0 7.0		12.0	0.0		+2.0 k€ DAQ, e-Logbook collaboration	
Materiale	Consumo	licenze software (Windows XP Embebbed, LabVIEW) modulistica CAN e kit di sviluppo sistemi ottici e movimentazioni	3.0 5.0		8.0	0.0		 components for the optical resolution test-stand camera objective remote control 	
Trasp. e facch.					0.0	0.0			
Spese	Calcolo	Consorzio Ore CPU Spazio Disco Cassette Altro	-		0.0	0.0			
Affitti e manutenz. apparecchiat.					0.0	0.0			
Materiale inventariabile		telecamera digitale Alta Risoluzione e software di controllo PC104 + kit di sviluppo server rack-mounting scheda IEEE1394 per il controllo della telecamera cavi IEEE1394 alta qualità e ripetitore ottico IEEE1394	4.5 2.5 3.0 3.0		13.0	0.0		+1.5 k€ Switch Gigabit Ethernet +2.0 k€ RAID system	
Costruzione Apparati					0.0	0.0			
Totale 36.0 0.0 41.5 k€ (total) Sono previsti interventi e/o impiantistica che ricadono sotto la disciplina della legge Merloni ? □ 41.5 k€ (total)									
Mod EC./EN. 2 (a cura del responsabile locale)									